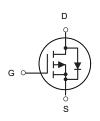


## Description

The SM3303PSQGC-TRG uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V.This device is suitable for use as a Battery protection or in other Switching application.

DFN3X3-8L (WDFN-8(3x3))



P-Channel MOSFET

#### **General Features**

 $V_{DS} = -30V$   $I_{D} = -55A$ 

 $R_{DS(ON)}$  < 11m $\Omega$  @  $V_{GS}$ =-10V

# **Application**

Battery protection

Load switch

Uninterruptible power supply

## **Package Marking and Ordering Information**

Product ID	Pack	Brand	Qty(PCS)
SM3303PSQGC-TRG	DFN3X3-8L(WDFN-8(3x3))	HXY MOSFET	5000

### Absolute Maximum Ratings (T<sub>c</sub>=25 ℃ unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	-30	V
VGS	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	-55	А
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	-23	А
IDM	Pulsed Drain Current <sup>2</sup>	-140	А
EAS	Single Pulse Avalanche Energy³	78.8	mJ
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	21.5	W
TSTG	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
R₀JC	Thermal Resistance Junction-Case <sup>1</sup>	5.8	°C/W



## P-Channel Enhancement Mode MOSFET

# **Electrical Characteristics** (T<sub>J</sub>=25 °C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V,I <sub>D</sub> = -250μA	-30	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = -30V, V_{GS} = 0V,$	-	-	-1	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS}$ = $V_{GS}$ , $I_{D}$ = -250 $\mu$ A	-1.0	-1.5	-2.5	V
D	Static Drain-Source on-Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-12A	-	8.5	11	mΩ
R <sub>DS(on)</sub>	note3	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-8A	-	13	18	11177
C <sub>iss</sub>	Input Capacitance	\/ - 45\/ \/ - 0\/	-	2800	-	pF
Coss	Output Capacitance	$V_{DS} = -15V, V_{GS} = 0V,$	-	346	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f = 1.0MHz	-	319	-	pF
Qg	Total Gate Charge	V <sub>DS</sub> = -15V, I <sub>D</sub> = -20A,	-	30	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	5.3	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge	V <sub>GS</sub> = -10V	-	7.6	-	nC
t <sub>d(on)</sub>	Turn-on Delay Time		-	14	-	ns
t <sub>r</sub>	Turn-on Rise Time	$V_{DD} = -15V, I_D = -20A,$	-	20	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time	$V_{GS}$ =-10V, $R_{GEN}$ =2.5 $\Omega$	-	95	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	65	-	ns
	Maximum Continuous Drain to Source Diode Forward Current					Δ.
l <sub>S</sub>			-	-	-55	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-140	Α
$V_{SD}$	Drain to Source Diode Forward	$V_{GS} = 0V, I_{S} = -35A$	_	-0.8	-1.2	V
	Voltage	VGS - UV, 15 - UUA		0.0	1.4	

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

- 2. EAS condition: T<sub>J</sub>= 25  $^{\circ}$ C, VDD= -20V, VG= -10V, L= 0.5mH, RG= 25  $^{\circ}$ C, IAS= -17A
- 3. Pulse Test: Pulse Width≤300µs, Duty Cycle≤2%



# P-Channel Enhancement Mode MOSFET

## **Typical Performance Characteristics**

Figure1: Output Characteristics

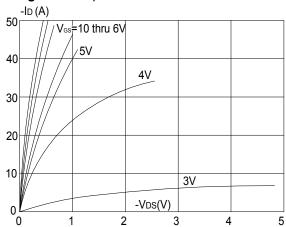


Figure 2: Typical Transfer Characteristics

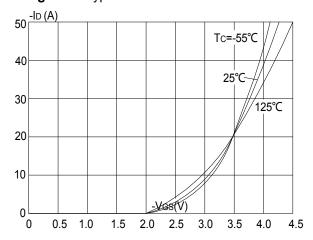


Figure 3:On-resistance vs. Drain Current

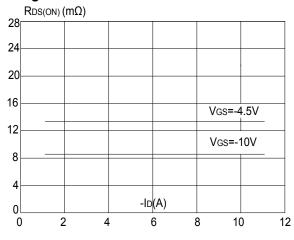


Figure 4: Body Diode Characteristics

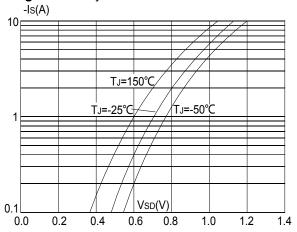


Figure 5: Gate Charge Characteristics

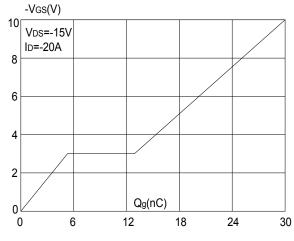
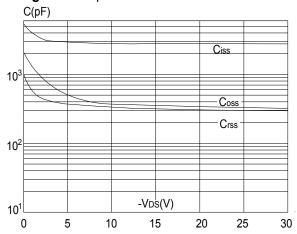


Figure 6: Capacitance Characteristics



## P-Channel Enhancement Mode MOSFET

**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature

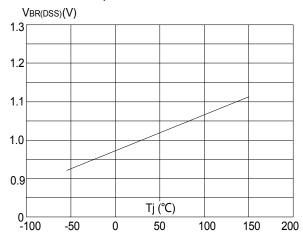
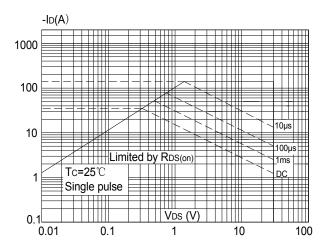
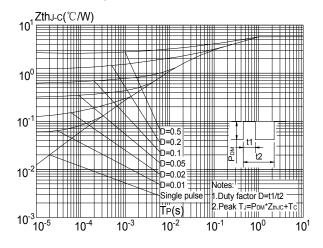


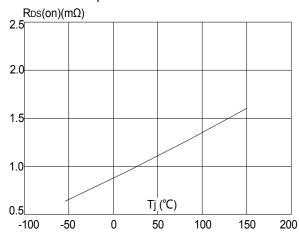
Figure 9: Maximum Safe Operating Area



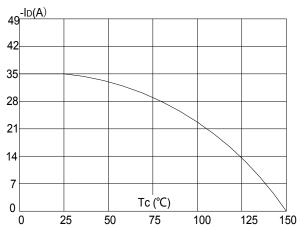
**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



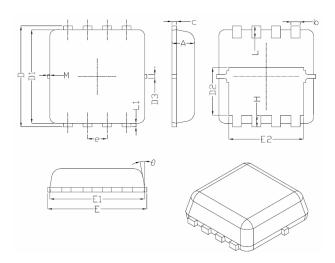
**Figure 8:** Normalized on Resistance vs. Junction Temperature



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



# DFN3X3-8L(W DFN-8(3x3)) Package Information



Symbol	Dimensions In Millimeters			
	Min.	Nom.	Max.	
A	0.70	0.75	0.80	
b	0.25	0.30	0.35	
С	0.10	0.15	0.25	
D	3.25	3.35	3.45	
D1	3.00	3.10	3.20	
D2	1.48	1.58	1.68	
D3	-	0.13	-	
E	3.20	3.30	3.40	
E1	3.00	3.15	3.20	
E2	2.39	2.49	2.59	
е	0.65BSC			
Н	0.30	0.39	0.50	
L	0.30	0.40	0.50	
L1	-	0.13	-	
М	*	*	0.15	
θ		10°	12 <sup>°</sup>	

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